

Appl. No. 10/780,512
Reply to Office Action of April 6, 2005

Attorney Docket No. 2003.0461 / 24061.520
Customer No. 42717

Amendments to the Specification

Please replace the paragraph at lines 1-9 on page 6 with the following amended paragraph:

Fig. 8A shows a third preferred embodiment of the present invention. Seal ring 81 has a first width A on the edges of the die and a second width C at the corner of the die. The corner width C is thicker than the width A. In this embodiment, the wide corner area covers the entire corner section of the seal ring. Also in this embodiment, a slot 83 is formed within the wide corner area. The slot can further reduce stress caused by the large wide metal corner section. Figs. 8B and 8C show other examples of slot and/or hole formations that can be used to reduce metal stress. It will be understood by those skilled in the art that a number of different slot and/or hole configurations could be used in the process of the present invention. In Fig. 8B, two semiconductor devices SD are shown diagrammatically at 86 and 87, where the semiconductor device 86 is located inside the seal ring 81, and the semiconductor device 87 is located outside the seal ring 81.